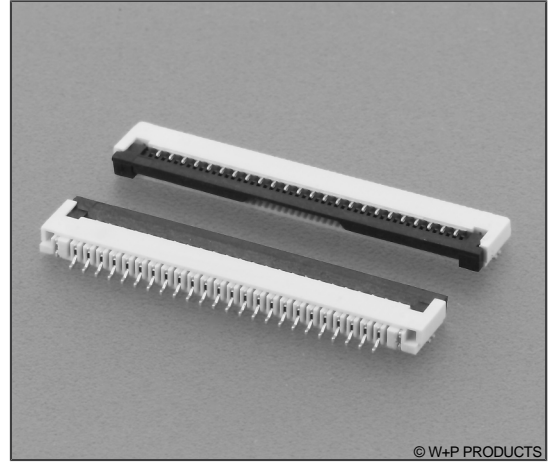


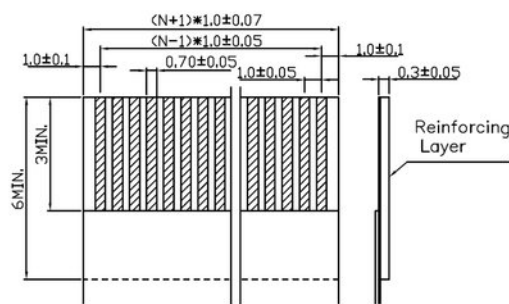
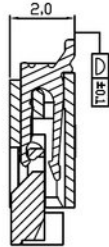
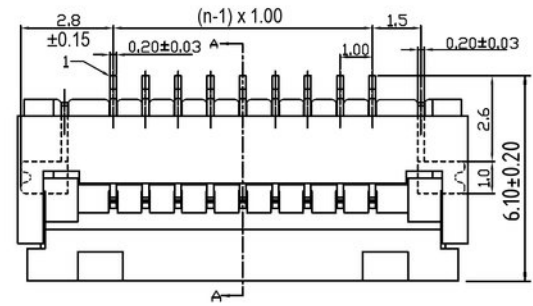
## SMT ZIF-Steckverbinder RM 1,00mm, liegend – Klappverriegelung SMT ZIF-Connectors, 1.00mm Pitch, horizontal – Flap Lock

### Technische Daten / Technical Data

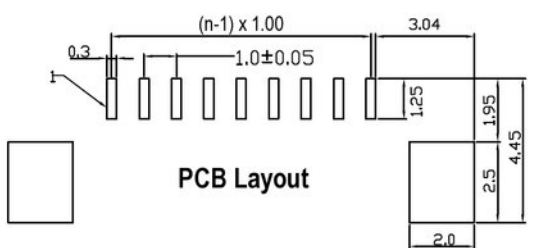
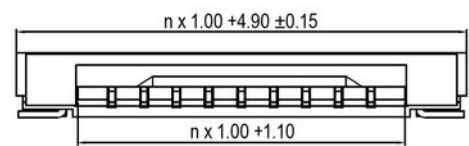
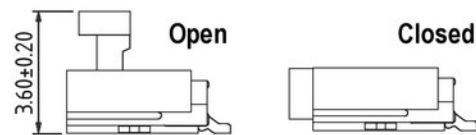
Gehäuse	Thermoplast, nach UL94 V-0
Shell	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Verzinkt
Contact Surface	Tin plated
Durchgangswiderstand	< 20mΩ
Contact Resistance	< 20mΩ
Isolationswiderstand	> 500MΩ
Insulation Resistance	> 500MΩ
Spannungsfestigkeit	200V <sub>AC</sub>
Test Voltage	200V <sub>AC</sub>
Nennspannung	50V AC/DC
Voltage Rating	50V AC/DC
Nennstrom	0,4A AC/DC
Current Rating	0.4A AC/DC
Temperaturbereich	-25°C ... +85°C
Temperature Range	-25°C ... +85°C



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Rcmd. FFC



PCB Layout

Kontaktierung unten  
Bottom Contacts

Series

**5533**

Contacts\*

**20**

04-30

Package

**TR**

TR Tape & Reel  
Tape & Reel

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** - please replace by your specifications.

# Informationen zum Reflow-Lötverfahren

## Reflow Soldering Information

### Reflow-Lötempfehlung

#### Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150°C
Temperatur Maximum $T_{Smax}$	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich $T_L$	217°C
Verweildauer oberhalb $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur $T_P$	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur $T_P$	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150°C
Maximum Temperatur $T_{Smax}$	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature $T_L$	217°C
Duration above $T_L$	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature $T_P$	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. $T_P$	Max. 8min

